

ABSTRACT OF THE DISCLOSURE

1
2 A heat dissipation method is provided for an electronic apparatus
3 including a housing, a circuit board mounted in the housing, and a heatsink
4 device mounted between and rested on the housing and the circuit board. The
5 heatsink device includes a heatsink plate having a bottom face rested on a
6 surface of the housing, and a heat conductive plate having a bottom face rested
7 on a top face of the heatsink plate and a top face rested on a bottom face of the
8 circuit board. Thus, the heatsink device dissipates the heat produced by the
9 heat sources of the circuit board largely and rapidly, thereby enhancing the heat
10 dissipation effect of the electronic apparatus.